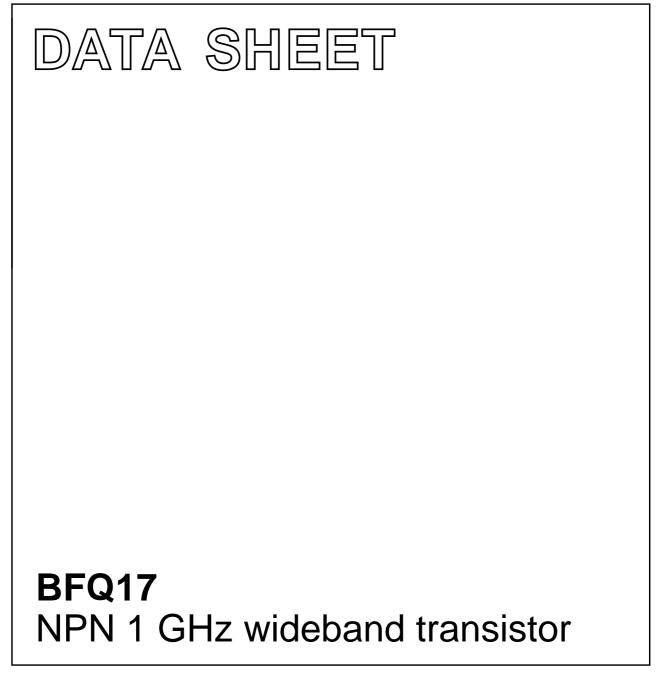
DISCRETE SEMICONDUCTORS



Product specification File under Discrete Semiconductors, SC14 September 1995



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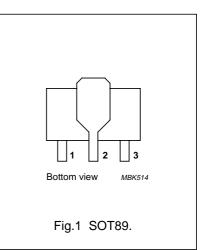
Philips Semiconductors

## BFQ17

## DESCRIPTION

NPN transistor in a SOT89 plastic envelope intended for application in thick and thin-film circuits. The transistor has extremely good intermodulation properties and a high power gain.

PINNING				
PIN	DESCRIPTION			
Code: FA				
1	emitter			
2	collector			
3	base			



### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	25	V
I <sub>CM</sub>	peak collector current		_	300	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 145 \ ^{\circ}C$ (note 1)	-	1	W
f <sub>T</sub>	transition frequency	$I_{C}$ = 150 mA; $V_{CE}$ = 15 V; f = 500 MHz; $T_{j}$ = 25 $^{\circ}\text{C}$		-	GHz
C <sub>re</sub>	feedback capacitance	$I_{C}$ = 10 mA; $V_{CE}$ = 15 V; f = 1 MHz; $T_{amb}$ = 25 °C	1.9	_	pF

## LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	40	V
V <sub>CER</sub>	collector-emitter voltage	$R_{BE} \le 50 \ \Omega$	-	40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	25	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	2	V
I <sub>C</sub>	DC collector current		-	150	mA
I <sub>CM</sub>	peak collector current	f > 1 MHz	-	300	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 145 \ ^\circ C$ (note 1)	-	1	W
T <sub>stg</sub>	storage temperature		-65	150	°C
Tj	junction temperature		_	175	°C

#### Note

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1.  $T_s$  is the temperature at the soldering point of the collector tab.

BFQ17

## NPN 1 GHz wideband transistor

### THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
	thermal resistance from junction to soldering point	up to $T_s = 145 \ ^\circ C$ (note 1)	30 K/W

#### Note

1.  $\ensuremath{ T_s}$  is the temperature at the soldering point of the collector tab.

### **CHARACTERISTICS**

 $T_j = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	$I_E = 0; V_{CB} = 20 V; T_j = 50 °C$	_	_	20	μA
V <sub>CE sat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 10 mA	-	-	0.5	V
h <sub>FE</sub>	DC current gain	$I_{C} = 150 \text{ mA}; V_{CE} = 5 \text{ V}$	25	80	-	
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0; V_{CB} = 15 V; f = 1 MHz$	-	-	4	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 10 mA; V <sub>CE</sub> = 15 V; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	1.9	-	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 150 mA; V <sub>CE</sub> = 15 V; f = 500 MHz	-	1.5	-	GHz
G <sub>UM</sub>	maximum unilateral power gain (note 1)	$I_{C} = 60 \text{ mA}; V_{CE} = 15 \text{ V};$ f = 200 MHz; T <sub>amb</sub> = 25 °C	-	16	-	dB
		I <sub>C</sub> = 60 mA; V <sub>CE</sub> = 15 V; f = 800 MHz; T <sub>amb</sub> = 25 °C	-	6.5	_	dB

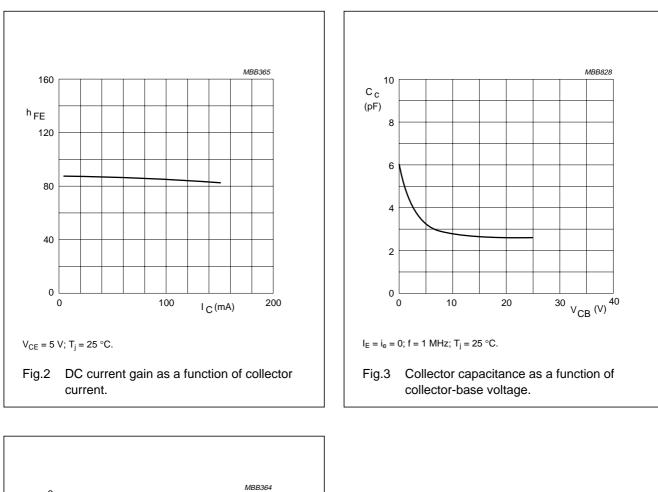
## Note

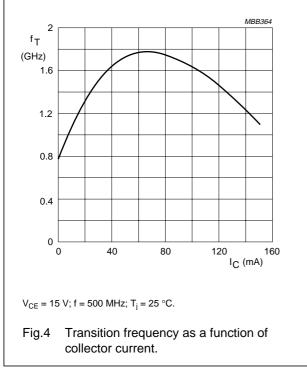
1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $S_{12}$  is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB$$

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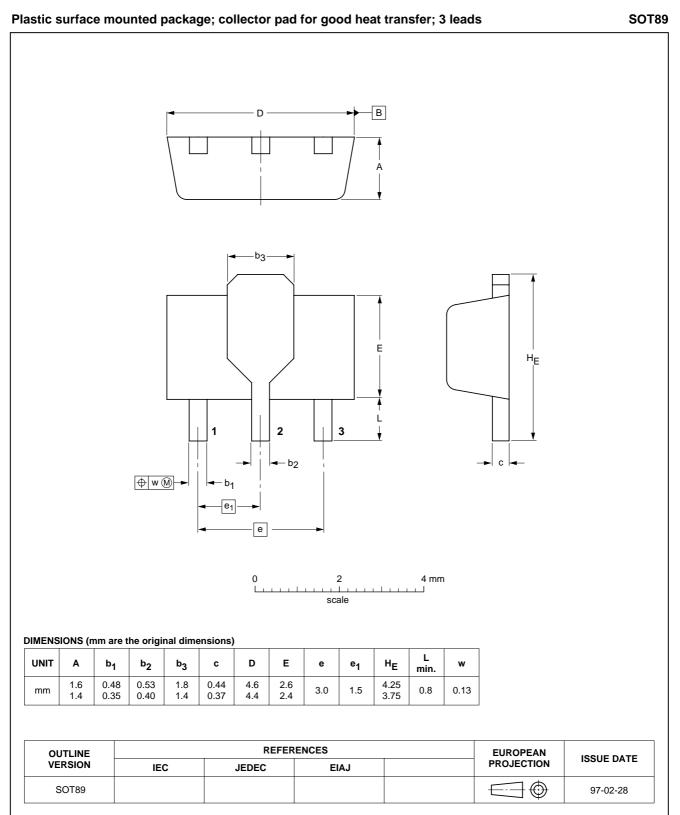
## BFQ17





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### PACKAGE OUTLINE



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## Objective specification Preliminary specification

DEFINITIONS

# Product specification Limiting values

**Data Sheet Status** 

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

This data sheet contains final product specifications.

This data sheet contains target or goal specifications for product development.

This data sheet contains preliminary data; supplementary data may be published later.

#### Application information

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.